

**THE EFFECT OF THE PROCESSING CONDITIONS
ON THE MECHANICAL AND DIELECTRIC
PROPERTIES OF EPOXY FOAM**

WAN NUR FADILLA BINTI WAN HAMAD

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SCHOOL OF MATERIALS ENGINEERING
UNIVERSITI MALAYSIA PERLIS

2011



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by

WAN NUR FADILLA BINTI WAN HAMAD

(1031620003)

A thesis submitted

In partial fulfillment of the requirement for the degree
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SUPERVISOR:

DR. TEH PEI LENG

Proposal Submitted in
Partial Fulfillment of the Requirements for the
Final Year Project

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